



News from El-Cat Inc.

We have a new Grinder !

It is Strasbaugh 7AA, so not really new, but we have learned how to make it do modern magic.

- We can coarse and fine grind wafers 3", 4" and 6" diameter to a precision of $\pm 1\mu\text{m}$.
- We learned how to grind wafers as thin as $100\mu\text{m}$.
- We made thickness standards, 25 wafers from $100\mu\text{m}$ to $580\mu\text{m}$ in steps of $20\mu\text{m}$.
- We have been using it with our wafer warp reduction techniques to produce 6" wafers with Warp $< 5\mu\text{m}$.

Here is what ground wafer surface looks like;

